

L Number	Hits	Search Text	DB	Time stamp
24	1	("6351390").PN.	USPAT; US-PGPUB; EPO; JPO	2002/09/30 15:07
25	10713	"flow sensor"	USPAT; US-PGPUB; EPO; JPO	2002/09/30 18:27
26	2660	"flow sensor" and housing	USPAT; US-PGPUB; EPO; JPO	2002/09/30 15:07
27	377	("flow sensor" and housing) and semiconductor	USPAT; US-PGPUB; EPO; JPO	2002/09/30 17:56
28	6	((("flow sensor" and housing) and semiconductor) and (seal\$4 ring) near4 semiconductor	USPAT; US-PGPUB; EPO; JPO	2002/09/30 15:30
29	0	20020043710.URPN.	USPAT	2002/09/30 15:08
30	0	5871627.URPN.	USPAT	2002/09/30 15:12
31	0	5871627.URPN.	USPAT	2002/09/30 15:12
32	3277	"strip conductor"	USPAT; US-PGPUB; EPO; JPO	2002/09/30 15:31
34	7	("strip conductor" and 73/\$7.ccls.) and semiconductor	USPAT; US-PGPUB; EPO; JPO	2002/09/30 16:19
33	52	"strip conductor" and 73/\$7.ccls.	USPAT; US-PGPUB; EPO; JPO	2002/09/30 17:49
35	36	("strip conductor" and 73/\$7.ccls.) and spac\$3	USPAT; US-PGPUB; EPO; JPO	2002/09/30 17:49
36	19	((("strip conductor" and 73/\$7.ccls.) and spac\$3) and force	USPAT; US-PGPUB; EPO; JPO	2002/09/30 17:49
37	39	((("flow sensor" and housing) and semiconductor) and (glue paste)	USPAT; US-PGPUB; EPO; JPO	2002/09/30 17:56
38	102	("flow sensor" and housing) and (ridg\$3 bump tip) near4 (housing enclosure chamber body plate mount\$4)	USPAT; US-PGPUB; EPO; JPO	2002/09/30 18:29
39	26	((("flow sensor" and housing) and (ridg\$3 bump tip) near4 (housing enclosure chamber body plate mount\$4)) and (semiconductor silicon)	USPAT; US-PGPUB; EPO; JPO	2002/09/30 18:29

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